DRA4143X (Tentative)

Silicon PNP epitaxial planar type

For digital circuits

Packaging

Radial type: 5000 pcs / carton

Absolute Maximum Ratings $T_a = 25^{\circ}C$

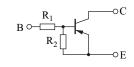
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	-50	V
Collector-emitter voltage (Base open)	V _{CEO}	-50	V
Collector current	I _C -100		mA
Total power dissipation	P _T	300	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg} -55 to +150		°C

Package

- Code
- NS-B1-B
- Pin Name 1: Emitter
 - 2: Collector
 - 3: Base

Marking Symbol: L6

Internal Connection



Resistance	R ₁	4.7	kΩ
value	R ₂	10	kΩ

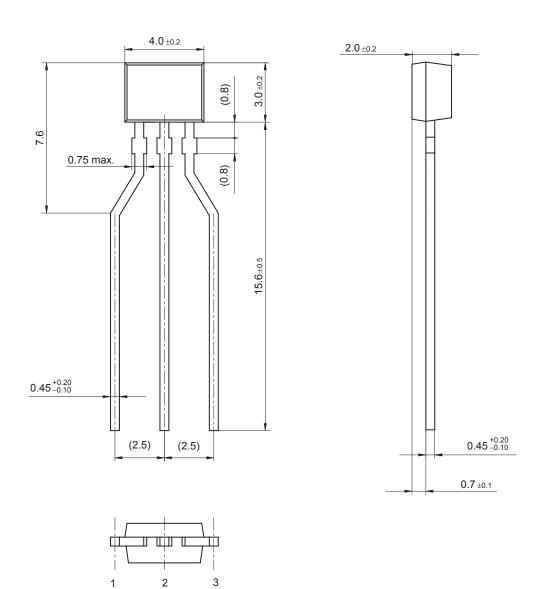
$\blacksquare Electrical Characteristics T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu {\rm A}, I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 {\rm mA}, I_{\rm B} = 0$	-50			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -50 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{\rm CE} = -50$ V, $I_{\rm B} = 0$			- 0.5	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{\rm EB} = -6$ V, $I_{\rm C} = 0$			-1.0	mA
Forward current transfer ratio	\mathbf{h}_{FE}	$V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$	30			_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -0.5 \text{ mA}$			-0.25	V
Input voltage (ON)	V _{I(on)}	$V_{CE} = -0.2 \text{ V}, I_C = -5 \text{ mA}$	-1.7			V
Input voltage (OFF)	V _{I(off)}	$V_{CE} = -5 V, I_C = -100 \mu A$			- 0.6	V
Input resistance	R ₁		-30%	4.7	+30%	kΩ
Resistance ratio	R_1/R_2		0.37	0.47	0.57	_

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

NS-B1-B

Unit: mm



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